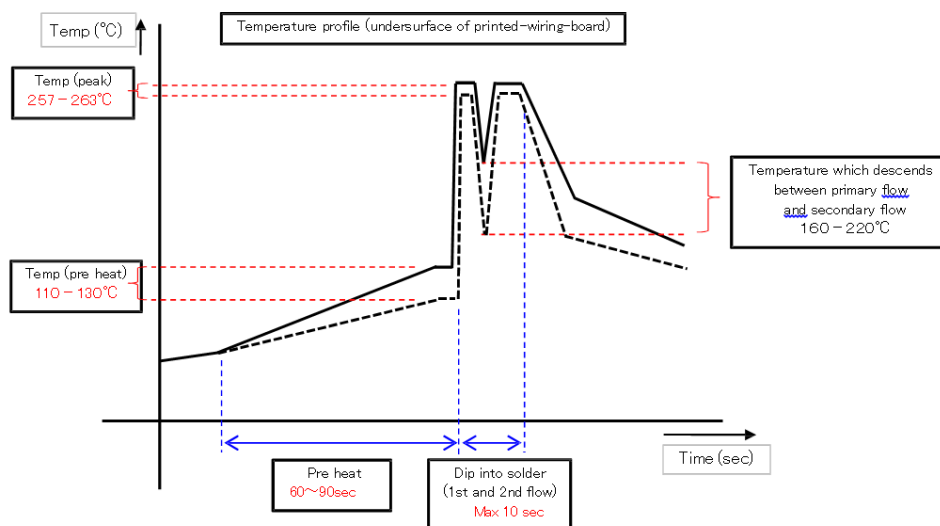


Recommended Condition for Flow Soldering (Mounting with Pb-Free solder)

Wave Soldering

Subject devices	:	Both Pb & Pb-free plated devices
Subject solder	:	Pb-free (SAC) solder
Temperature	:	Max. 260°C, max 10 sec Preheat 110-130°C, 60-90 sec (for single sided boards 100 ±10°C) (max temp increase ≤ 3°C/sec)

References



Application of heat shall be made within the retention time in accordance with JEDEC MSL level (260± 3°C) printed on the identification label of packing.
 Note : Depending on the package types, flow soldering may not be applicable.
 For details, refer to the description on soldering in the data sheet of the products.